



for

LED



xLED

xLED-LUME-8030 Pin Fin Heat Sink Φ 80mm for Lumens

Features VS Benefits

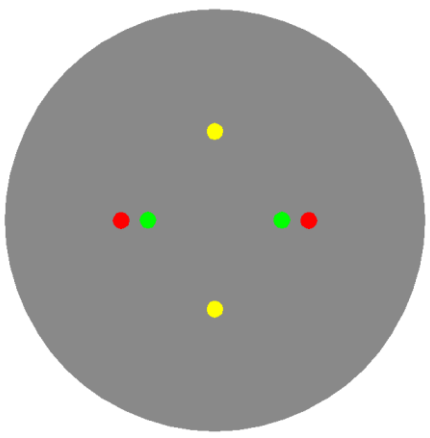
- * The xLED-LUME-8030 Lumens Pin Fin LED Heat Sinks are specifically designed for luminaires using the Lumens LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,000 to 2,600 lumen.
- * Thermal resistance range Rth 3.13°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Lumens Ergon COB series, and AC-ALL series LED engines.
- * Diameter 80.0mm - standard height 30.0mm Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Lumens COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

LUMENS



Lumens LED Modules directly Mounting Options

Lumens Ergon COB_HO, COB_HO+, COB_HE Series :
 ERC1812xxxxHO; ERC1812xxxxHE;
 ERC1820xxxxHO; ERC1820xxxxHE;
 With the Zhaga Book 3 holders for the red indicator marks.
 (Ideal Holder:50-2101CR); (BJB holder:47.319.2131.50);
 Without the holders for the green indicator marks.
 Direct mounting with machine screws M3x6.5mm.

Lumens Ergon COB_HO, COB_HO+, COB_HE Series :
 ERC2520xxxxHO; ERC2530xxxxHE;
 ERC2530xxxxHO; ERC2540xxxxHE;
 ERC2540xxxxHO; ERC2530xxxxHO+
 ERC2520xxxxHO+
 With the Zhaga Book 3 holders for the red indicator marks.
 (Ideal Holder:50-2102CR); (BJB Holder:47.319.2141.50);
 Without the holders for the yellow indicator marks.
 Direct mounting with machine screws M3x6.5mm.

Lumens AC-ALL Series :
 EDC/47C/15W /xxx/120V/B; EDC/47C/15W /xxx/230V/A;
 EDC/57C/20W /xxx/120V/B; EDC/57C/20W /xxx/230V/A;
 EDC/57C/30W /xxx/120V/B; EDC/57C/30W /xxx/230V/A;
 With the Zhaga Book 3 holders for the red indicator marks.
 Direct mounting with machine screws M3x6.5mm.
 Please refer to the www.lumensleds.com data provided on the manual.



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Mounting Options and Drawings & Dimensions

Example: xLED-LUME-8030-B-1,2

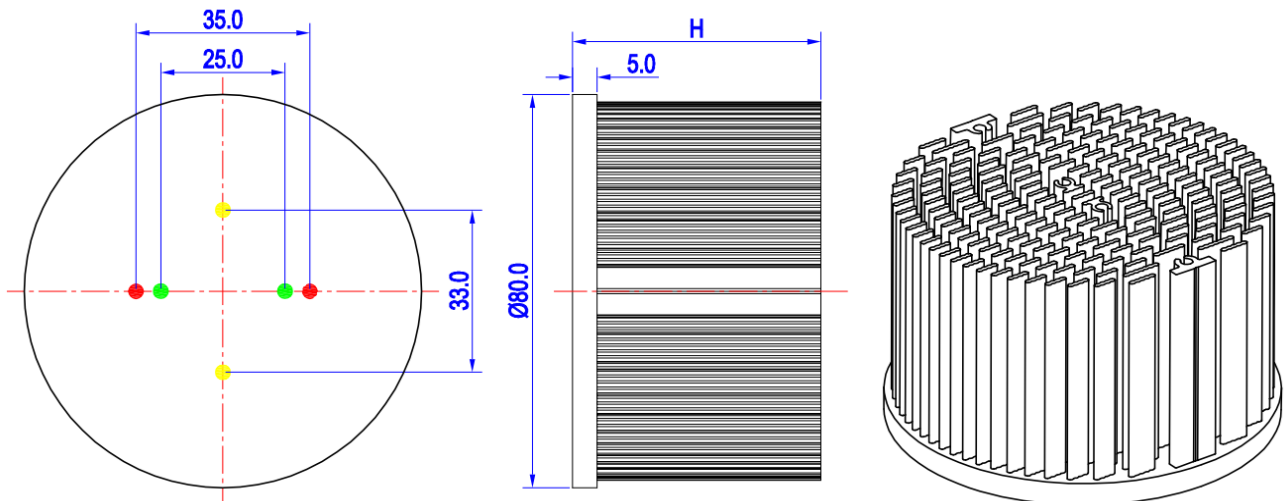
Example: xLED-LUME-80 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
 - B-Black
 - C-Clear
 - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
Ex.order code - 12
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	Ergon COB (17.85x17.85)	/	M3	6.5mm	25.0mm/ 2-@180°
2	Ergon COB (23.85x23.85)	/	M3	6.5mm	33.0mm/ 2-@180°
3	AC-ALL Series	Lumens	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	Ergon COB (17.85x17.85)	BJB Holder 47.319.2131.50			
		Ideal Holder 50-2101CR			
	Ergon COB (23.85x23.85)	BJB Holder 47.319.2141.50			
Ideal Holder 50-2102CR					



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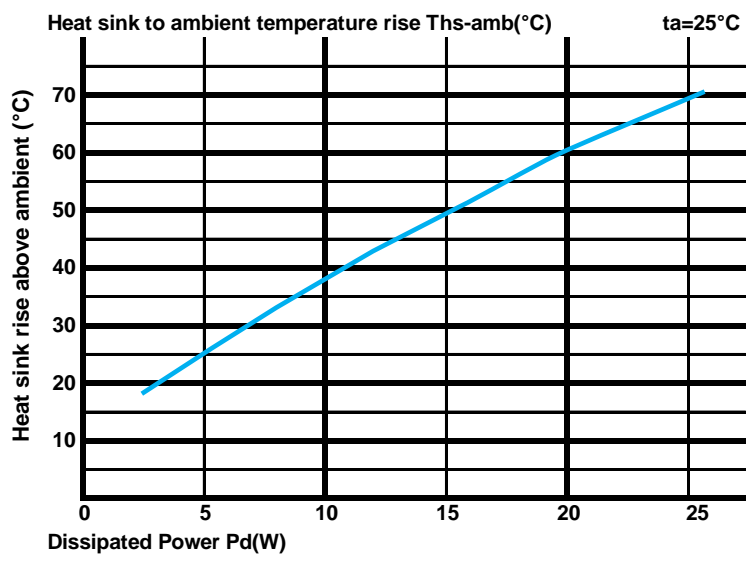
The product data table

	Model No.	xLED-LUME-8030
	Heatsink Size	Φ80xH30mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	140.0
	Dissipated power (Ths-amb,50°C)	16.0 (W)
	Cooling surface area (mm²)	72123
	Thermal Resistance (Rhs-amb)	3.13 (°C/W)

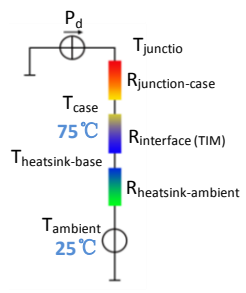
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
 *To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).
 Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

Dissipated Power Pd(W)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)		Heat sink to ambient temperature rise Ths-amb (°C)	
	xLED-LUME-8030			
5.0	5.00		25.0	
10.0	3.80		38.0	
15.0	3.27		49.0	
20.0	3.00		60.0	
25.0	2.76		69.0	



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
 MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
 Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.
 Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta) / Pd$
 θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
 *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].
 *Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:
 $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$